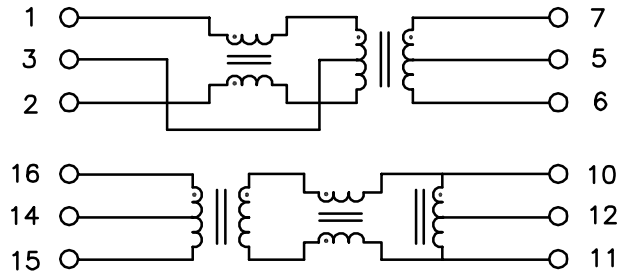


DIMENSIONS : Inch [mm]
CO-PLANARITY : 0.004 [0.10]



PART NO. : TG22-S143NDRL

16PIN SMT ISOLATION MODULE FOR 10/100BASE-TX
IEEE802.3u APPLICATIONS

LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

OPERATING TEMPERATURE 0/+70°C

ELECTRICAL SPECIFICATIONS @25° C

TURN RATIO

TX P16-15:P10-11

1CT:1.41CT±3%

RX P1-2:P7-6

1CT:1CT±3%

OCL (100KHz,0.1Vrms,8mA)

P7-6,P10-11

350µH min

DCR P7-6,P16-15

0.9Ω max

LL P1-2,P16-15

0.4µH max

Cw/w

20pF typ

CROSSTALK 0.1-100MHz

-40dB typ

CMR 0.1-100MHz

-40dB typ

ISOLATION

1,500Vrms

HALO/PBL

TITLE ISOLATION MODULE

FOR FAST ETHERNET

PART NO. TG22-S143NDRL

SCALE NONE PAGE 1 OF 2

SIGNATURES

DRAWN PETER LU

CHECKED

APPROVED

FILE S143NDRL.DWG

DATE

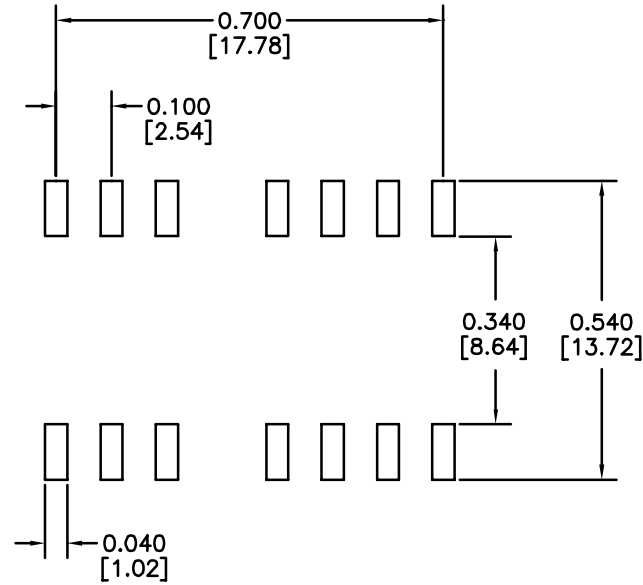
4/28/05

REV.

A

DESC.

DATE



RECOMMENDED SOLDER PAD DIMENSIONS
 DIMENSIONS: Inch [mm]

HALO/PBL	TITLE ISOLATION MODULE		SIGNATURES		DATE	REV.	DESC.	DATE
	FOR FAST ETHERNET		DRAWN PETER LU		4/28/05	A		
	PART NO. TG22-S143NDRL		CHECKED					
	SCALE NONE		PAGE 2 OF 2		APPROVED			
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE		FILE S143NDRL.DWG						